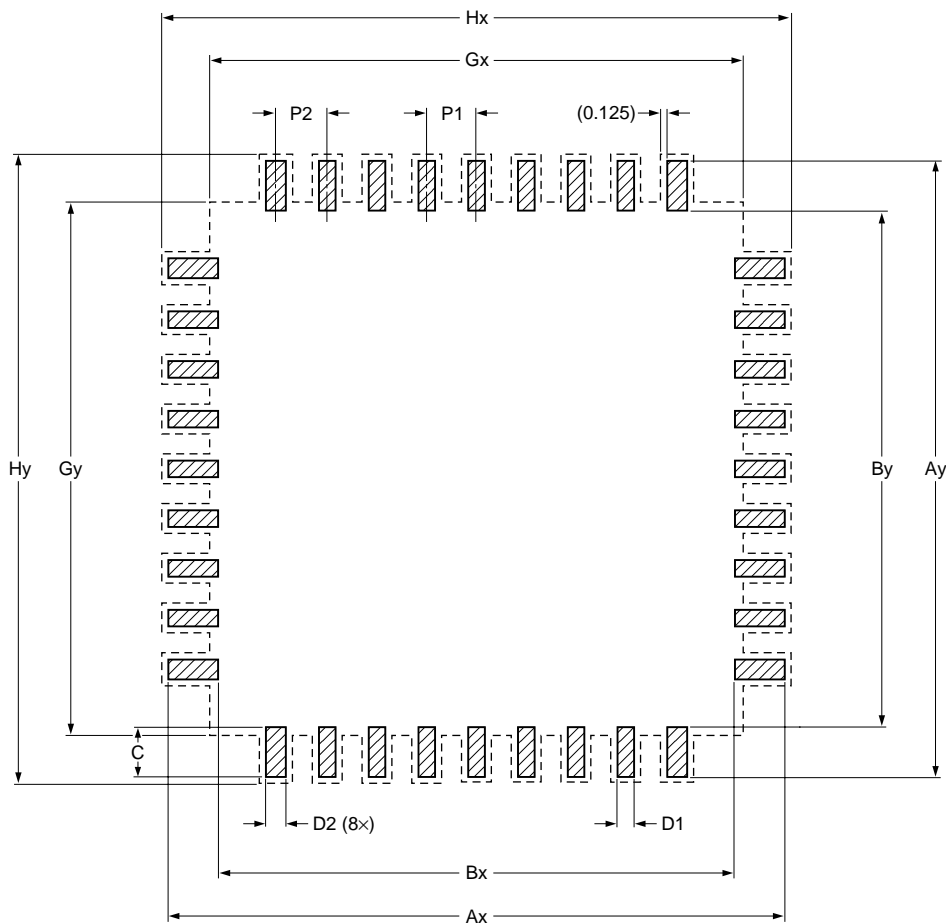



Footprint information for reflow soldering of LQFP144 package

SOT486-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
- - - - occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	23.300	23.300	20.300	20.300	1.500	0.280	0.400	20.500	20.500	23.550	23.550